



2-input / 1-output 3dB hybrid combiner is used for same band systems combination. This hybrid combiner covers the frequency band of 1710-2170MHz, with high isolation and low PIM performance. It is a double-unit mechanical design for 2T2R MIMO applications.

General Specifications

Product Type Double-Unit Low PIM Hybrid Combiner

Frequency Band 1710-2170 MHz

2-input / 1-output ×2 Input / Output Intermodulation (3rd order) ≤-150dBc@2×43dBm

Connector Interface N female

Electrical Specifications

Frequency Band 1710-2170 MHz ≤-19.1 dB Return Loss **VSWR** ≤1.25 Insertion Loss ≤0.2 dB **Distribution Loss** Nominal 3 dB

Distribution Loss Ripple ±0.3 dB Isolation ≥25 dB

Intermodulation (3rd order) ≤-150dBc@2×43dBm **Power Handling** 100 watts per port

Impedance 50 ohms

Material Specifications

Cavity **Cavity Enclosure** Aluminum alloy

> Conductive oxidation / Painting Cavity Outer Surface Treatment

Cavity Inner Surface Treatment Cu3Ag1

Inner Conductor Aluminum alloy

Inner Conductor Surface Treatment Ag1

Connector **Outer Conductor** Brass

Inner Conductor

Outer Conductor Surface Treatment Tri-metal CuSnZn3

Brass

Inner Conductor Surface Treatment Ag1

Insulator PTFE/TPX Gasket Silicon rubber



Mechanical Specifications

Dimension 140×204×91 mm

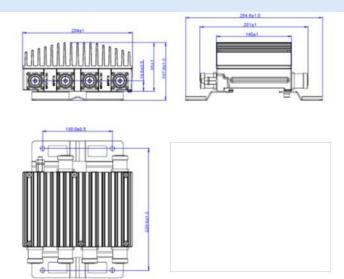
Weight 5 kg
Connectors Type N female
Mounting Bracket
Packing 1pcs in box

Environmental Specifications

Operating Temperature $-40 \,^{\circ}\text{C}$ to $+65 \,^{\circ}\text{C}$ Storage Temperature $-45 \,^{\circ}\text{C}$ to $+85 \,^{\circ}\text{C}$ Relative Humidity 5% - 95%

Application IP65

Outline Drawing



Regulatory Compliances

ISO 9001:2015 Compliant ROHS Compliant China RoHS Compliant UK RoHS Compliant REACH Compliant EU/CE Compliant

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